

Claims

1. A silicone adhesive for bonding a semiconductor pellet to a member for mounting the pellet, which comprises an addition reaction curing silicone rubber composition contaminating, upon curing by heating, a glass plate therewith at a contact angle of 70°C or less to the glass plate.

2. The silicone adhesive according to claim 1, wherein the addition reaction curing silicone rubber composition comprises:

- (A) organopolysiloxane having, in one molecule, two or more silicon atom-bound alkenyl groups; 100 parts by weight,
- (B) organopolysiloxane having, in one molecule, two or more silicon atom-bound hydrogen atoms, which shows 5 wt% or less loss in weight upon heating at 100°C for 1 hour; an amount enough to supply 0.5 to 3 silicon atom-bound hydrogen atoms in component (B) per alkenyl group in component (A),
- (C) a tackifier having silicon atom-bound alkoxy groups and not having silicon atom-bound hydrogen atoms; 0.1 to 10 parts by weight, and
- (D) a platinum-based catalyst; a catalytic amount.

3. The silicone adhesive according to claim 1, wherein the addition reaction curing silicone rubber composition comprises:

- (A) organopolysiloxane having, in one molecule, two or more silicon atom-bound alkenyl groups; 100 parts by weight,

(B) organopolysiloxane having, in one molecule, two or more silicon atom-bound hydrogen atoms, which shows 5 wt% or less loss in weight upon heating at 100°C for 1 hour; an amount enough to supply 0.5 to 3 silicon atom-bound hydrogen atoms in component (B) per alkenyl group in component (A),

(D) a platinum-based catalyst; a catalytic amount,

(E) a tackifier; 0.1 to 10 parts by weight, and

(F) an Al or Ti compound; 0.05 to 10 parts by weight.

4. A method of bonding a semiconductor pellet to a member for mounting the pellet by a silicone adhesive comprising an addition reaction curing silicone rubber composition contaminating, upon curing by heating, a glass plate therewith at a contact angle of 70°C or less to the glass plate.

5. Use of an addition reaction curing silicone rubber composition contaminating, upon curing by heating, a glass plate therewith at a contact angle of 70°C or less to the glass plate as a silicone adhesive for bonding a semiconductor pellet to a member for mounting the pellet.